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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	1568
Total RAM Bits	25600
Number of I/O	221
Number of Gates	48000
Voltage - Supply	3V ~ 3.6V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/or3t306ba256i-db

Table of Contents

Contents	Page	Contents	Page
Features	1	PCM Detailed Programming	78
System-Level Features.....	4	PCM Applications	81
Description.....	5	PCM Cautions	82
FPGA Overview	5	FPGA States of Operation.....	83
PLC Logic	5	Initialization	83
Description (continued).....	6	Configuration	84
PIC Logic	6	Start-Up	85
System Features	6	Reconfiguration	86
Routing	6	Partial Reconfiguration	86
Configuration	6	Other Configuration Options	86
Description (continued).....	7	Using ispLEVER to Generate	86
ispLEVER Development System	7	Configuration RAM Data	87
Architecture	7	Configuration Data Frame	87
Programmable Logic Cells	9	Bit Stream Error Checking	89
Programmable Function Unit	9	FPGA Configuration Modes.....	90
Look-Up Table Operating Modes	11	Master Parallel Mode	90
Supplemental Logic and Interconnect Cell (SLIC).....	19	Master Serial Mode	91
PLC Latches/Flip-Flops	23	Asynchronous Peripheral Mode	92
PLC Routing Resources	25	Microprocessor Interface (MPI) Mode	92
PLC Architectural Description	32	Slave Serial Mode	95
Programmable Input/Output Cells.....	34	Slave Parallel Mode	95
5 V Tolerant I/O	35	Daisy-Chaining	96
PCI Compliant I/O	35	Daisy-Chaining with Boundary Scan	97
Inputs	36	Absolute Maximum Ratings.....	98
Outputs	39	Recommended Operating Conditions	98
PIC Routing Resources	42	Electrical Characteristics	99
PIC Architectural Description	43	Timing Characteristic Description	101
High-Level Routing Resources	45	Description	101
Interquad Routing	45	PFU Timing	102
Programmable Corner Cell Routing	46	PLC Timing	109
PIC Interquad (MID) Routing	47	SLIC Timing	109
Clock Distribution Network	48	PIO Timing	110
PFU Clock Sources	48	Special Function Blocks Timing	113
Clock Distribution in the PLC Array	49	Clock Timing	121
Clock Sources to the PLC Array	50	Configuration Timing	131
Clocks in the PICs	50	Readback Timing	140
ExpressCLK Inputs	51	Input/Output Buffer Measurement Conditions	141
Selecting Clock Input Pins	51	Output Buffer Characteristics	142
Special Function Blocks	52	OR3Cxx	142
Single Function Blocks	52	OR3Txxx	143
Boundary Scan	55	Estimating Power Dissipation	144
Microprocessor Interface (MPI)	62	OR3Cxx	144
PowerPC System	63	OR3Txxx.....	145
i960 System	64	Pin Information	147
MPI Interface to FPGA	65	Pin Descriptions.....	147
MPI Setup and Control	66	Package Compatibility	151
Programmable Clock Manager (PCM)	70	Compatibility with OR2C/TxxA Series	152
PCM Registers	71	Package Thermal Characteristics.....	188
Delay-Locked Loop (DLL) Mode	73	FPGA Maximum Junction Temperature	190
Phase-Locked Loop (PLL) Mode	74	Package Coplanarity	191
PCM/FPGA Internal Interface	77	Package Parasitics	191
PCM Operation	77	Package Outline Diagrams.....	192

Programmable Logic Cells (continued)

Look-Up Table Operating Modes

The operating mode affects the functionality of the PFU input and output ports and internal PFU routing. For example, in some operating modes, the DIN[7:0] inputs are direct data inputs to the PFU latches/FFs. In memory mode, the same DIN[7:0] inputs are used as a 4-bit write data input bus and a 4-bit write address input bus into LUT memory.

Table 3 lists the basic operating modes of the LUT. Figure 4—Figure 10 show block diagrams of the LUT operating modes. The accompanying descriptions demonstrate each mode's use for generating logic.

Table 3. Look-Up Table Operating Modes

Mode	Function
Logic	4- and 5-input LUTs; softwired LUTs; latches/FFs with direct input or LUT input; CIN as direct input to ninth FF or as pass through to COUT.
Half Logic/ Half Ripple	Upper four LUTs and latches/FFs in logic mode; lower four LUTs and latches/FFs in ripple mode; CIN and ninth FF for logic or ripple functions.
Ripple	All LUTs combined to perform ripple-through data functions. Eight LUT registers available for direct-in use or to register ripple output. Ninth FF dedicated to ripple out, if used. The submodes of ripple mode are adder/subtractor, counter, multiplier, and comparator.
Memory	All LUTs and latches/FFs used to create a 32 x 4 synchronous dual-port RAM. Can be used as single-port or as ROM.

PFU Control Inputs

Each PFU has five routable control inputs and an active-low, asynchronous global set/reset (GSRN) signal that affects all latches and FFs in the device. The five control inputs are CLK, LSR, CE, ASWE, and SEL, and their functionality for each logic mode of the PFU (discussed subsequently) is shown in Table 4. The clock signal to the PFU is CLK, CE stands for clock enable, which is its primary function. LSR is the local set/reset signal that can be configured as synchronous or asynchronous. The selection of set or reset is made for each latch/FF and is not a function of the signal itself. ASWE stands for add/subtract/write enable, which are its functions, along with being an optional clock enable, and SEL is used to dynamically select between direct PFU input and LUT output data as the input to the latches/FFs.

All of the control signals can be disabled and/or inverted via the configuration logic. A disabled clock enable indicates that the clock is always enabled. A disabled LSR indicates that the latch/FF never sets/resets (except from GSRN). A disabled SEL input indicates that DIN[7:0] PFU inputs are routed to the latches/FFs. For logic and ripple modes of the PFU, the LSR, CE, and ASWE (as a clock enable) inputs can be disabled individually for each nibble (latch/FF[3:0], latch/FF[7:4]) and for the ninth FF.

Programmable Logic Cells (continued)

Softwired LUT submode uses F4 and F5 LUTs and internal PFU feedback routing to generate complex logic functions up to three LUT-levels deep. Figure 3 shows multiplexers between the Kz[3:0] inputs to the PFU and the LUTs. These multiplexers can be independently configured to route certain LUT outputs to the input of other LUTs. In this manner, very complex logic functions, some of up to 21 inputs, can be implemented in a single PFU at greatly enhanced speeds.

Figure 5 shows several softwired LUT topologies. In this figure, each circle represents either an F4 or F5 LUT. It is important to note that an LUT output that is fed back for softwired use is still available to be registered or output from the PFU. This means, for instance, that a logic equation that is needed by itself and as a term in a larger equation need only be generated once and PLC routing resources will not be required to use it in the larger equation.

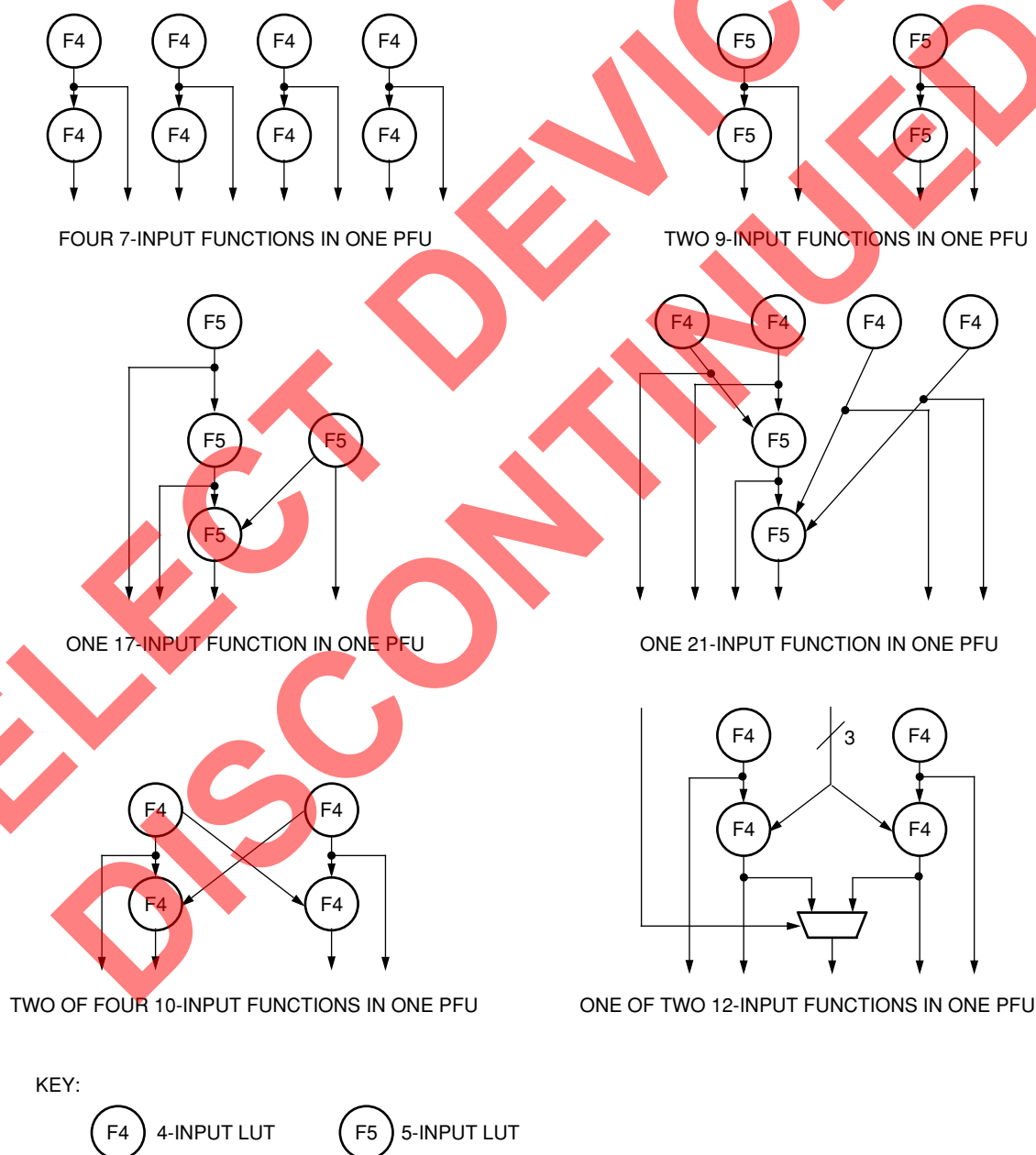


Figure 5. Softwired LUT Topology Examples

Programmable Input/Output Cells

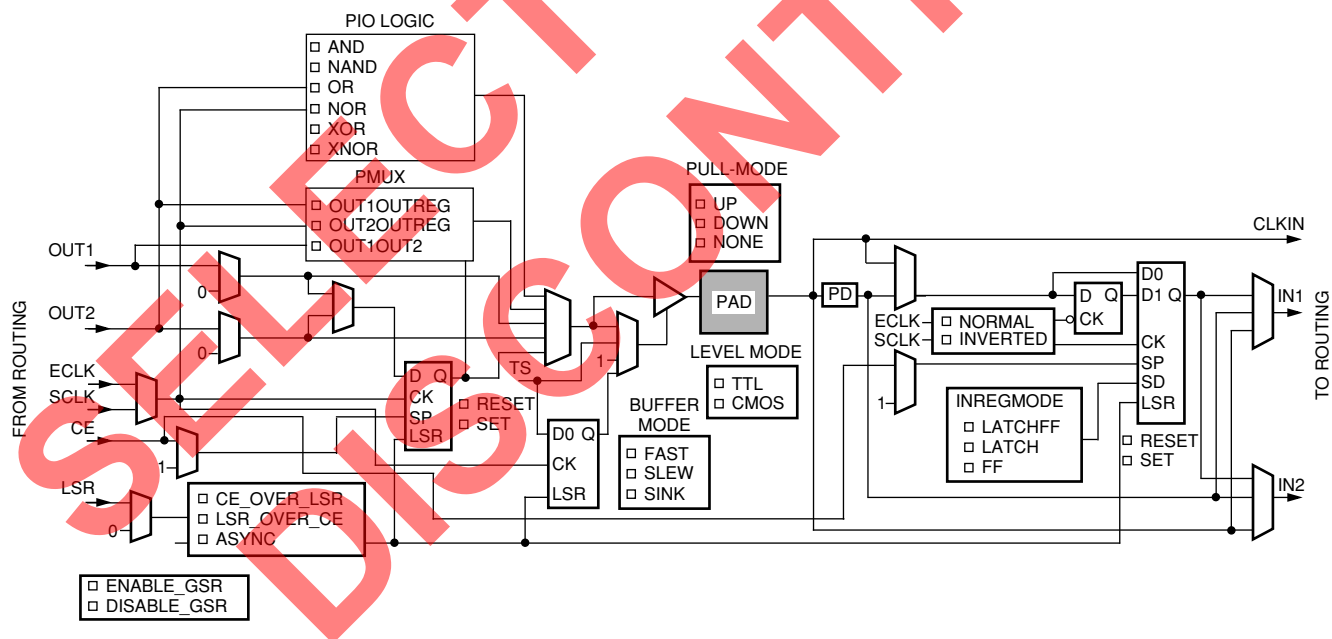
The programmable input/output cells (PICs) are located along the perimeter of the device. The PIC's name is represented by a two-letter designation to indicate on which side of the device it is located followed by a number to indicate in which row or column it is located. The first letter, P, designates that the cell is a PIC and not a PLC. The second letter indicates the side of the array where the PIC is located. The four sides are left (L), right (R), top (T), and bottom (B). The individual I/O pad is indicated by a single letter (either A, B, C, or D) placed at the end of the PIC name. As an example, PL10A indicates a pad located on the left side of the array in the tenth row.

Each PIC interfaces to four bond pads and contains the necessary routing resources to provide an interface between I/O pads and the PLCs. Each PIC is composed of four programmable I/Os (PIOs) and significant routing resources. Each PIO contains input buffers, output buffers, routing resources, latches/FFs, and logic and can be configured as an input, output, or bidirectional I/O.

PICs in the Series 3 FPGAs have significant local routing resources, similar to routing in the PLCs. This new routing increases the ability to fix user pinouts prior to placement and routing of a design and still maintain routability. The flexibility provided by the routing also provides for increased signal speed due to a greater variety of signal paths possible.

Included in the PIC routing is a fast path from the input pins to the SLICs in each of the three adjacent PLCs (one orthogonal and two diagonal). This feature allows for input signals to be very quickly processed by the SLIC decoder function and used on-chip or sent back off of the FPGA. Also new to the Series 3 PIOs are latches and FFs and options for using fast, dedicated clocks called ExpressCLKs. These features will all be discussed in subsequent sections.

A diagram of a single PIO (one of four in a PIC) is shown in Figure 22. Table 9 provides an overview of the programmable functions in an I/O cell.



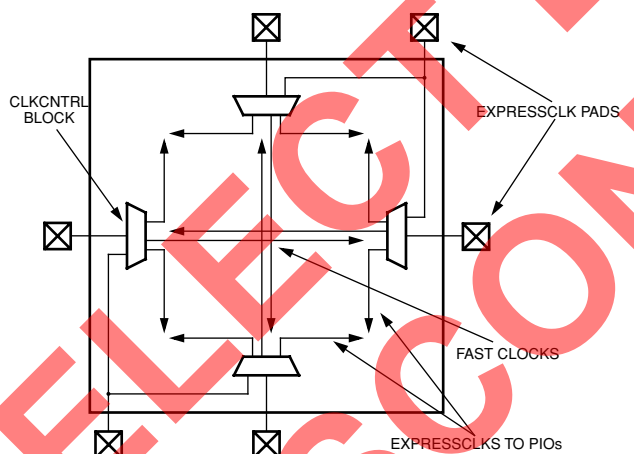
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Figure 22. OR3C/Txxx Programmable Input/Output (PIO) Image from ispLEVER

Clock Distribution Network (continued)

ExpressCLK Inputs

There are four dedicated ExpressCLK pads on each Series 3 device: one in the middle of each side. Two other user I/O pads can also be used as corner ExpressCLK inputs, one on the lower-left corner, and one on the upper-right corner. The corner ExpressCLK pads feed the ExpressCLK to the two sides of the array that are adjacent to that corner, always driving the same signal in both directions. The ExpressCLK route from the middle pad and from the corner pad associated with that side are multiplexed and can be glitchlessly stopped/started under user control using the StopCLK feature of the CLKNTRL function block (described under Special Function Blocks) on that side. The ExpressCLK output of the programmable clock manager (PCM) is programmably connected to the corner ExpressCLK routes. PCM blocks are found in the same corners as the corner ExpressCLK signals and are described in the Special Function Blocks section. The ExpressCLK structure is shown in Figure 34 (PCM blocks are not shown).



5-5802(F)

Note: All multiplexers are set during configuration.

Figure 34. ExpressCLK and Fast Clock Distribution

Selecting Clock Input Pins

Any user I/O pin on an ORCA FPGA can be used as a fast, low-skew system clock input. Since the four dedicated ExpressCLK inputs can only be used to distribute global signals into the FPGA, these pins should be selected first as clock pins. Within the interquad region of the device, these clocks sourced by the ExpressCLK inputs are called fast clocks. Choosing the next clock

pin is completely arbitrary, but using a pin that is near the center of an edge of the device will provide the lowest skew system clock network. The pin-to-pin timing numbers in the Timing Characteristics section assume that the clock pin is in one of the PICs at the center of any side of the device next to an ExpressCLK pad. For actual timing characteristics for a given clock pin, use the timing analyzer results from isplEVER.

To select subsequent clock pins, certain rules should be followed. As discussed in the Programmable Input/Output Cells section, PICs are grouped into adjacent pairs. Each of these pairs contains eight I/Os, but only one of the eight I/Os in a PIC pair can be routed directly onto a system clock spine. Therefore, to achieve top performance, the next clock input chosen should not be one of the pins from a PIC pair previously used for a clock input. If it is necessary to have a second input in the same PIC pair route onto global system clock routing, the input can be routed to a free clock spine using the PIC switching segment (pSW) connections to the clock spine network at some small sacrifice in speed. Alternatively, if global distribution of the secondary clock is not required, the signal can be routed on long lines (xL) and input to the PFU clock input without using a clock spine.

Another rule for choosing clock pins has to do with the alternating nature of clock spine connections to the xL and pxL routing segments. Starting at the left side of the device, the first vertical clock spine from the top connects to hxL[0] (horizontal xL[0]), and the first vertical clock spine from the bottom connects to hxL[5] in all PLC rows. The next vertical clock spine from the top connects to hxL[1], and the next one from the bottom connects to hxL[6]. This progression continues across the device, and after a spine connects to hxL[9], the next spine connects to hxL[0] again. Similar connections are made from horizontal clock spines to vxL (vertical xL) lines from the top to the bottom of the device. Because the ORCA Series 3 clock routing only requires the use of an xL line in every other row or column, even two inputs chosen 20 PLCs apart on the same xL line will not conflict, but it is always better to avoid these choices, if possible. The fast clock spines in the interquad routing region also connect to xL[8] and xL[9] for each set of xL lines, so it is better to avoid user I/Os that connect to xL[8] or xL[9] when a fast clock is used that might share one of these connections.

Another reason to use the fast clock spines is that since they use only the xL[9:8] lines, they will not conflict with internal data buses which typically use xL[7:0]. For more details on clock selection, refer to application notes on clock distribution in ORCA Series 3 devices.

Special Function Blocks (continued)

The external test (EXTEST) instruction allows the interconnections between ICs in a system to be tested for opens and stuck-at faults. If an EXTEST instruction is performed for the system shown in Figure 36, the connections between U1 and U2 (shown by nets a, b, and c) can be tested by driving a value onto the given nets from one device and then determining whether the same value is seen at the other device. This is determined by shifting 2 bits of data for each pin (one for the output value and one for the 3-state value) through the BSR until each one aligns to the appropriate pin. Then, based upon the value of the 3-state signal, either the I/O pad is driven to the value given in the BSR, or the BSR is updated with the input value from the I/O pad, which allows it to be shifted out TDO.

The SAMPLE/PRELOAD instruction is useful for system debugging and fault diagnosis by allowing the data at the FPGA's I/Os to be observed during normal

operation or written during test operation. The data for all of the I/Os is captured simultaneously into the BSR, allowing them to be shifted-out TDO to the test host. Since each I/O buffer in the PICs is bidirectional, two pieces of data are captured for each I/O pad: the value at the I/O pad and the value of the 3-state control signal. For preload operation, data is written from the BSR to all of the I/Os simultaneously.

There are five ORCA-defined instructions. The PLC scan rings 1 and 2 (PSR1, PSR2) allow user-defined internal scan paths using the PLC latches/FFs. The RAM_Write Enable (RAM_W) instruction allows the user to serially configure the FPGA through TDI. The RAM_Read Enable (RAM_R) allows the user to read back RAM contents on TDO after configuration. The IDCODE instruction allows the user to capture a 32-bit identification code that is unique to each device and serially output it at TDO. The IDCODE format is shown in Table 14.

Table 14. Boundary-Scan ID Code

Device	Version (4 bits)	Part* (10 bits)	Family (6 bits)	Manufacturer (11 bits)	LSB (1 bit)
OR3T20	0000	0011000000	110000	00000011101	1
OR3T30	0000	0111000000	110000	00000011101	1
OR3T55	0000	0100100000	110000	00000011101	1
OR3C/T80	0000	0110100000	110000	00000011101	1
OR3T125	0000	0011100000	110000	00000011101	1

* PLC array size of FPGA, reverse bit order.

Note: Table assumes version 0.

Programmable Clock Manager (PCM)

(continued)

PCM Applications

The applications discussed below are only a small sampling of the possible uses for the PCM. Check the Lattice website for additional application notes.

Clock Phase Adjustment

The PCM may be used to adjust the phase of the input clock. The result is an output clock which has its active edge either preceding or following the active edge of the input clock. Clock phase adjustment is accomplished in DLL mode by delaying the clock. This is discussed in the Delay-Locked Loop (DLL) Mode section. Examples of using the delayed clock as an early or late phase-adjusted clock are outlined in the following paragraphs.

An output clock that precedes the input clock can be used to compensate for clock delay that is largely due to excessive loading. The preceding output clock is really not early relative to the input clock, but is delayed almost a full cycle. This is shown in Figure 48A. The amount of delay that is being compensated for, plus

clock setup time and some margin, is the amount **less** than one full clock cycle that the output clock is delayed from the input clock.

In some systems, it is desirable to operate logic from several clocks that operate at different phases. This technique is often used in microprocessor-based systems to transfer and process data synchronously between functional areas, but without incurring excessive delays. Figure 48B shows an input clock and an output clock operating 180° out of phase. It also shows a version of the input clock that was shifted approximately 180° using logic gates to create an inverter. Note that the inverted clock is really shifted more than 180° due to the propagation delay of the inverter. The PCM output clock does not suffer from this delay. Additionally, the 180° shifted PCM output could be shifted by some smaller amount to effect an early 180° shifted clock that also accounts for loading effects.

In terms of degrees of phase shift, the phase of a clock is adjustable in DLL mode with resolution relative to the delay increment (see Table 27):

$$\text{Phase Adjustment} = (\text{Delay}) * 11.25, \quad \text{Delay} < 16$$

$$\text{Phase Adjustment} = ((\text{Delay}) * 11.25) - 360, \quad \text{Delay} > 16$$

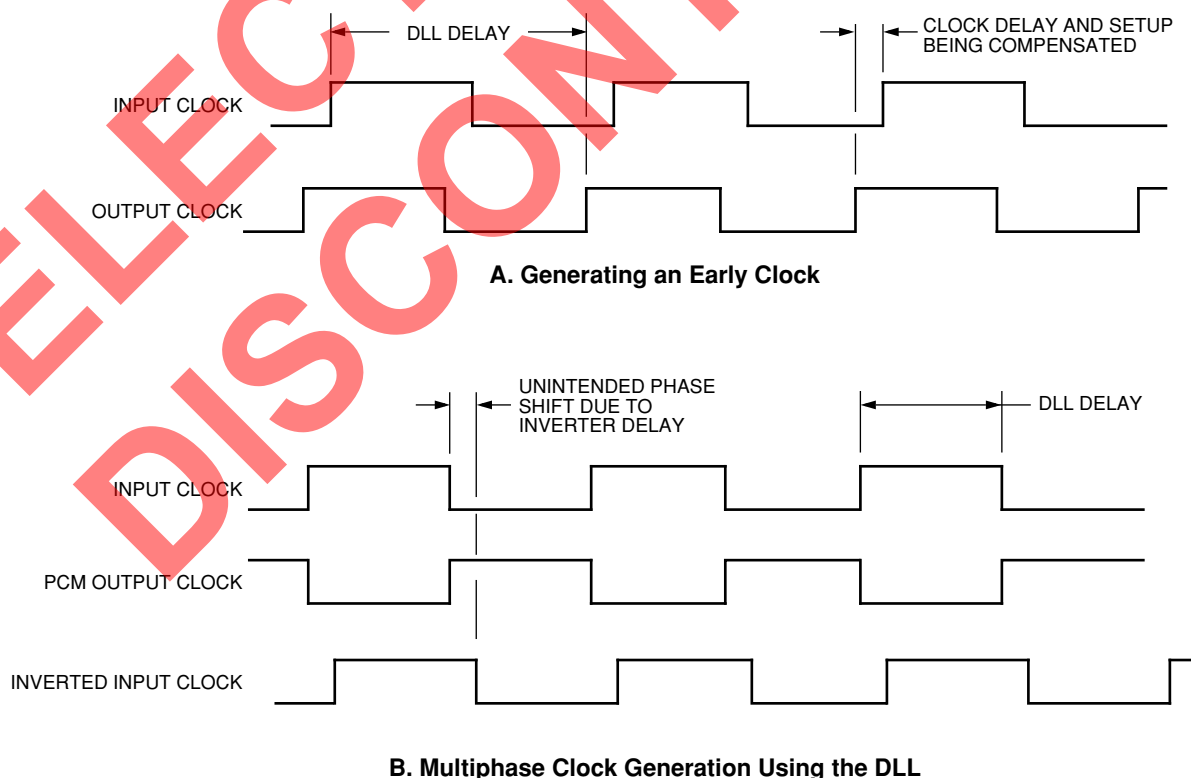
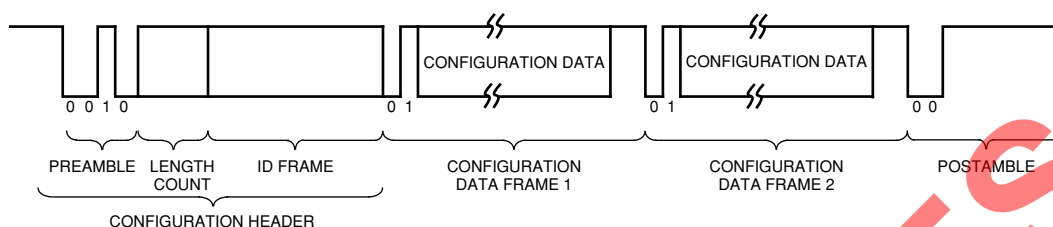


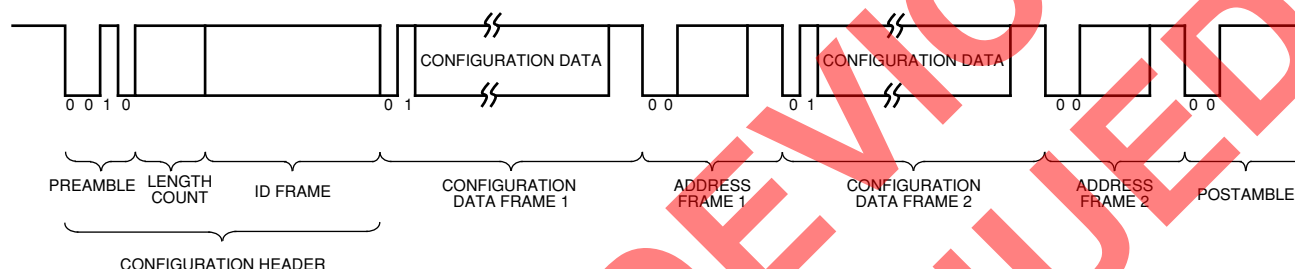
Figure 48. Clock Phase Adjustment Using the PCM

Configuration Data Format (continued)



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Figure 52. Serial Configuration Data Format—Autoincrement Mode



5-5760(F)

Figure 53. Serial Configuration Data Format—Explicit Mode

Table 32. Configuration Frame Format and Contents

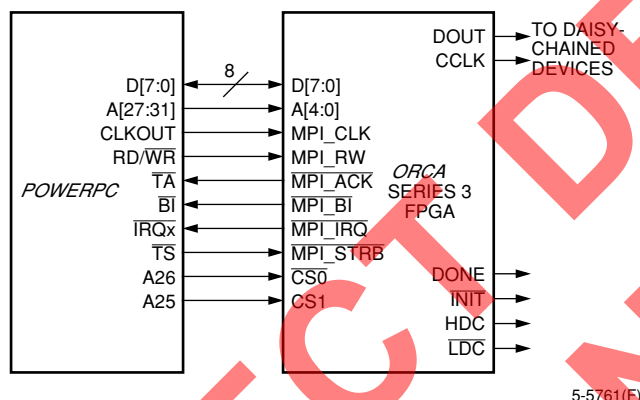
Header	11110010	Preamble
	24-bit Length Count	Configuration frame length.
	11111111	Trailing header—8 bits.
ID Frame	0101 1111 1111 1111	ID frame header.
	Configuration Mode	00 = autoincrement, 01 = explicit.
	Reserved [41:0]	Reserved bits set to 0.
	ID	20-bit part ID.
	Checksum	8-bit checksum.
Configuration Data Frame (repeated for each data frame)	11111111	Eight stop bits (high) to separate frames.
	01	Data frame header.
	Data Bits	Number of data bits depends upon device.
	Alignment Bits = 0	String of 0 bits added to bit stream to make frame header, plus data bits reach a byte boundary.
	Checksum	8-bit checksum.
Configuration Address Frame	11111111	Eight stop bits (high) to separate frames.
	00	Address frame header.
	14 Address Bits	14-bit address of location to start data storage.
	Checksum	8-bit checksum.
Postamble	11111111	Eight stop bits (high) to separate frames.
	00	Postamble header.
	11111111 111111	Dummy address.
	1111111111111111	16 stop bits.*

* In MPI configuration mode, the number of stop bits = 32.

Note: For slave parallel mode, the byte containing the preamble must be 11110010. The number of leading header dummy bits must be $(n * 8) + 4$, where n is any nonnegative integer and the number of trailing dummy bits must be $(n * 8)$, where n is any positive integer. The number of stop bits/frame for slave parallel mode must be $(x * 8)$, where x is a positive integer. Note also that the bit stream generator tool supplies a bit stream that is compatible with all configuration modes, including slave parallel mode.

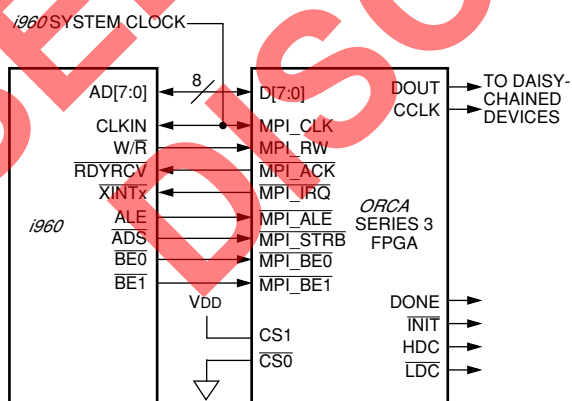
FPGA Configuration Modes (continued)

There are two options for using the host interrupt request in configuration mode. The configuration control register offers control bits to enable the interrupt on either a bit stream error or to notify the host processor when the FPGA is ready for more configuration data. The MPI status register may be used in conjunction with, or in place of, the interrupt request options. The status register contains a 2-bit field to indicate the bit stream error status. As previously mentioned, there is also a bit to indicate the MPI's readiness to receive another byte of configuration data. A flow chart of the MPI configuration process is shown in Figure 59. The MPI status and configuration register bit maps can be found in the Special Function Blocks section and MPI configuration timing information is available in the Timing Characteristics section of this data sheet.



Note: FPGA shown as a memory-mapped peripheral using CS0 and CS1. Other decoding schemes are possible using CS0 and/or CS1.

Figure 57. PowerPC MPI Configuration Schematic



Note: FPGA shown as only system peripheral with fixed chip select signals. For multiperipheral systems, address decoding and/or latching can be used to implement chip selects.

Figure 58. i960 MPI Configuration Schematic

Configuration readback can also be performed via the MPI when it is in user mode. The MPI is enabled in user mode by setting the MP_USER bit to 1 in the configuration control register prior to the start of configuration or through a configuration option. To perform readback, the host processor writes the 14-bit readback start address to the readback address registers and sets the RD_CFG bit to 0 in the configuration control register. Readback data is returned 8 bits at a time to the readback data register and is valid when the DATA_RDY bit of the status register is 1. There is no error checking during readback. A flow chart of the MPI readback operation is shown in Figure 60. The RD_DATA pin used for dedicated FPGA readback is invalid during MPI readback.

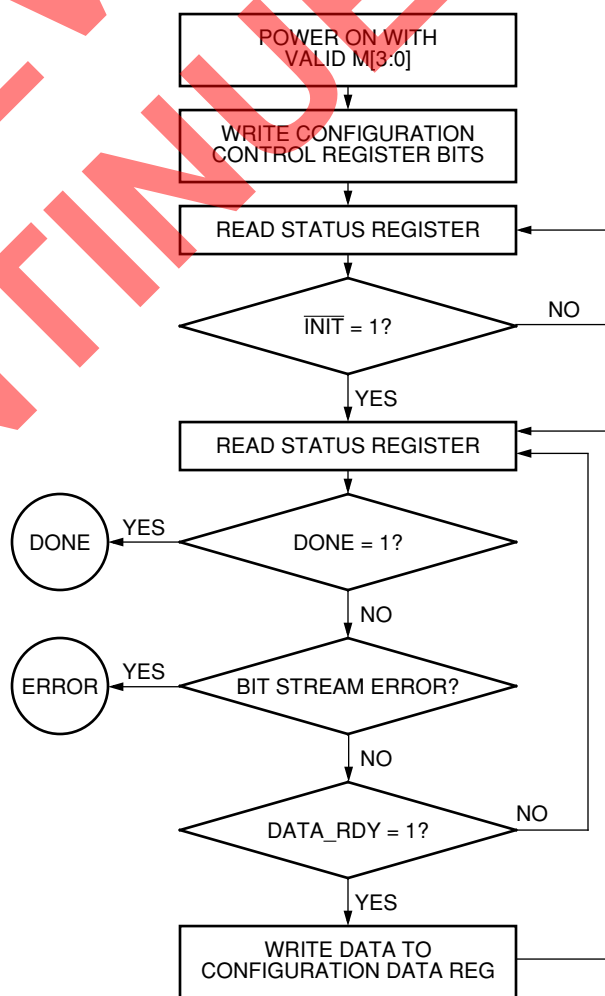


Figure 59. Configuration Through MPI

FPGA Configuration Modes (continued)

Slave Serial Mode

The slave serial mode is primarily used when multiple FPGAs are configured in a daisy-chain (see the Daisy-Chaining section). It is also used on the FPGA evaluation board that interfaces to the download cable. A device in the slave serial mode can be used as the lead device in a daisy-chain. Figure 61 shows the connections for the slave serial configuration mode.

The configuration data is provided into the FPGA's DIN input synchronous with the configuration clock CCLK input. After the FPGA has loaded its configuration data, it retransmits the incoming configuration data on DOUT. CCLK is routed into all slave serial mode devices in parallel.

Multiple slave FPGAs can be loaded with identical configurations simultaneously. This is done by loading the configuration data into the DIN inputs in parallel.

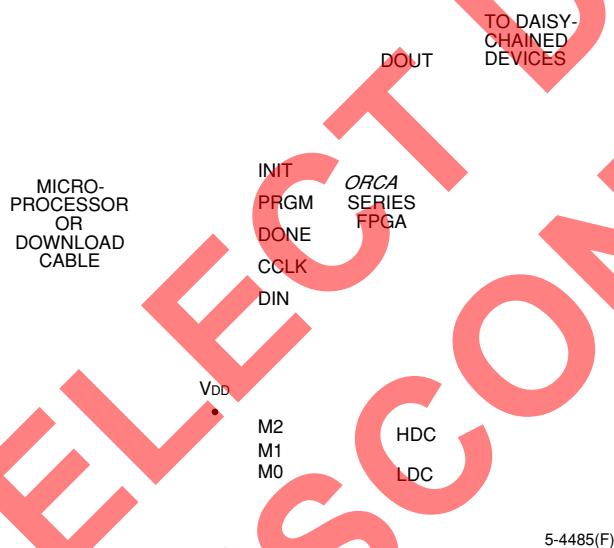


Figure 61. Slave Serial Configuration Schematic

Slave Parallel Mode

The slave parallel mode is essentially the same as the slave serial mode except that 8 bits of data are input on pins D[7:0] for each CCLK cycle. Due to 8 bits of data being input per CCLK cycle, the DOUT pin does not contain a valid bit stream for slave parallel mode. As a result, the lead device cannot be used in the slave parallel mode in a daisy-chain configuration.

Figure 62 is a schematic of the connections for the slave parallel configuration mode. \overline{WR} and $\overline{CS0}$ are active-low chip select signals, and CS1 is an active-high chip select signal. These chip selects allow the user to configure multiple FPGAs in slave parallel mode using an 8-bit data bus common to all of the FPGAs. These chip selects can then be used to select the FPGA(s) to be configured with a given bit stream. The chip selects must be active for each valid CCLK cycle until the device has been completely programmed. They can be inactive between cycles but must meet the setup and hold times for each valid positive CCLK. D[7:0] of the FPGA can be connected to D[7:0] of the microprocessor only if a standard prom file format is used. If a .bit or .rpt file is used from isplEVER, then the user must mirror the bytes in the .bit or .rpt file OR leave the .bit or .rpt file unchanged and connect D[7:0] of the FPGA to D[0:7] of the microprocessor.

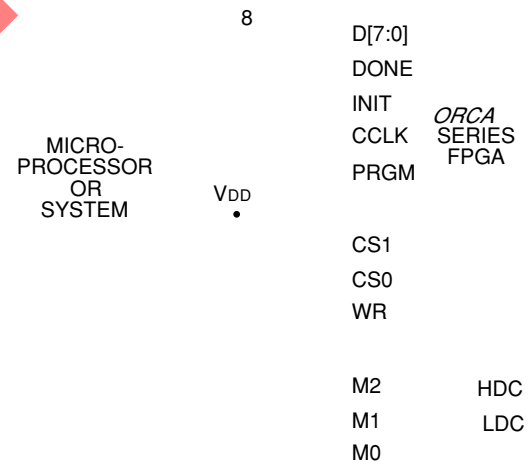


Figure 62. Slave Parallel Configuration Schematic

Timing Characteristics (continued)

Table 48. Programmable I/O (PIO) Timing Characteristics (continued)

OR3Cxx Commercial: VDD = 5.0 V ± 5%, 0 °C < TA < 70 °C; Industrial: VDD = 5.0 V ± 10%, -40 °C < TA < +85 °C.

OR3Txxx Commercial: VDD = 3.0 V to 3.6 V, 0 °C < TA < 70 °C; Industrial: VDD = 3.0 V to 3.6 V, -40 °C < TA < +85 °C.

Parameter	Symbol	Speed								Unit
		-4		-5		-6		-7		
		Min	Max	Min	Max	Min	Max	Min	Max	
Output Delays (TJ = 85 °C, VDD = min, CL = 50 pF)										
Output to Pad (OUT2, OUT1 direct to pad):										
Fast	OUTF_DEL	—	5.09	—	4.21	—	2.63	—	2.17	ns
Slewlim	OUTSL_DEL	—	7.86	—	6.49	—	3.49	—	2.91	ns
Sinklim	OUTSI_DEL	—	9.41	—	7.98	—	8.08	—	7.32	ns
3-state Enable/Disable Delay (TS to pad):										
Fast	TSF_DEL	—	4.93	—	4.09	—	2.33	—	1.88	ns
Slewlim	TSSL_DEL	—	7.70	—	6.37	—	3.00	—	2.41	ns
Sinklim	TSSI_DEL	—	9.25	—	7.86	—	7.95	—	7.23	ns
Local Set/Reset (async) to Pad (LSR to pad):										
Fast	OUTLSRF_DEL	—	9.03	—	7.25	—	4.96	—	3.94	ns
Slewlim	OUTLSRSL_DEL	—	11.79	—	9.53	—	5.82	—	4.67	ns
Sinklim	OUTLSRSI_DEL	—	13.35	—	11.02	—	10.38	—	9.10	ns
Global Set/Reset to Pad (GSRN to pad):										
Fast	OUTGSRF_DEL	—	8.30	—	6.69	—	4.39	—	3.46	ns
Slewlim	OUTGSRSL_DEL	—	11.06	—	8.97	—	5.07	—	3.99	ns
Sinklim	OUTGSRSI_DEL	—	12.62	—	10.46	—	10.02	—	8.81	ns
Output FF Setup Timing:										
Out to ExpressCLK (OUT[2:1] to ECLK)	OUTE_SET	0.00	—	0.00	—	0.00	—	0.00	—	ns
Out to Clock (OUT[2:1] to CLK)	OUT_SET	0.00	—	0.00	—	0.00	—	0.00	—	ns
Clock Enable to Clock (CE to CLK)	OUTCE_SET	0.91	—	0.67	—	0.56	—	0.45	—	ns
Local Set/Reset (sync) to Clock (LSR to CLK)	OUTLSR_SET	0.41	—	0.32	—	0.26	—	0.24	—	ns
Output FF Hold Timing:										
Out from ExpressCLK (OUT[2:1] from ECLK)	OUTE_HLD	0.73	—	0.58	—	0.36	—	0.29	—	ns
Out from Clock (OUT[2:1] from CLK)	OUT_HLD	0.73	—	0.58	—	0.36	—	0.29	—	ns
Clock Enable from Clock (CE from CLK)	OUTCE_HLD	0.00	—	0.00	—	0.00	—	0.00	—	ns
Local Set/Reset (sync) from Clock (LSR from CLK)	OUTLSR_HLD	0.00	—	0.00	—	0.00	—	0.00	—	ns
Clock to Pad Delay (ECLK, SCLK to pad):										
Fast	OUTREGF_DEL	—	6.71	—	5.44	—	3.56	—	2.78	ns
Slewlim	OUTREGSL_DEL	—	9.47	—	7.71	—	4.42	—	3.52	ns
Sinklim	OUTREGSI_DEL	—	11.03	—	9.20	—	8.98	—	7.94	ns
Additional Delay If Using Open Drain	OD_DEL	—	0.20	—	0.16	—	0.10	—	0.08	ns

Note: The delays for all input buffers assume an input rise/fall time of <1 V/ns.

Timing Characteristics (continued)

Table 54. OR3Cxx ExpressCLK to Output Delay (Pin-to-Pin)

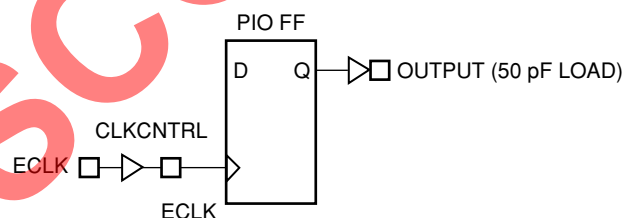
OR3Cxx Commercial: VDD = 5.0 V ± 5%, 0 °C < TA < 70 °C; Industrial: VDD = 5.0 V ± 10%, -40 °C < TA < +85 °C; CL = 50 pF.
OR3Txxx Commercial: VDD = 3.0 V to 3.6 V, 0 °C < TA < 70 °C; Industrial: VDD = 3.0 V to 3.6 V, -40 °C < TA < +85 °C; CL = 50 pF.

Description (TJ = 85 °C, VDD = min)	Device	Speed								Unit
		-4		-5		-6		-7		
		Min	Max	Min	Max	Min	Max	Min	Max	
ECLK Middle Input Pin→OUTPUT Pin (Fast)	OR3T20	—	—	—	7.78	—	5.40	—	4.38	ns
	OR3T30	—	—	—	7.84	—	5.43	—	4.40	ns
	OR3T55	—	9.93	—	7.96	—	5.48	—	4.44	ns
	OR3C/T80	—	10.10	—	8.08	—	5.54	—	4.49	ns
	OR3T125	—	—	—	8.28	—	5.64	—	4.58	ns
ECLK Middle Input Pin→OUTPUT Pin (Slewlim)	OR3T20	—	—	—	9.77	—	6.07	—	4.91	ns
	OR3T30	—	—	—	9.83	—	6.10	—	4.93	ns
	OR3T55	—	12.37	—	9.95	—	6.15	—	4.97	ns
	OR3C/T80	—	12.54	—	10.07	—	6.21	—	5.02	ns
	OR3T125	—	—	—	10.27	—	6.31	—	5.11	ns
ECLK Middle Input Pin→OUTPUT Pin (Sinklim)	OR3T20	—	—	—	11.12	—	10.92	—	9.65	ns
	OR3T30	—	—	—	11.18	—	10.95	—	9.67	ns
	OR3T55	—	13.73	—	11.30	—	11.00	—	9.71	ns
	OR3C/T80	—	13.90	—	11.42	—	11.06	—	9.76	ns
	OR3T125	—	—	—	11.62	—	11.16	—	9.85	ns
Additional Delay if ECLK Corner Pin Used	OR3T20	—	—	—	1.91	—	1.80	—	1.58	ns
	OR3T30	—	—	—	1.91	—	1.90	—	1.67	ns
	OR3T55	—	1.97	—	1.91	—	2.09	—	1.84	ns
	OR3C/T80	—	1.97	—	1.91	—	2.28	—	2.02	ns
	OR3T125	—	—	—	1.90	—	2.57	—	2.29	ns

Notes:

Timing is without the use of the programmable clock manager (PCM).

This clock delay is for a fully routed clock tree that uses the ExpressCLK network. It includes both the input buffer delay, the clock routing to the PIO CLK input, the clock→Q of the FF, and the delay through the output buffer. The given timing requires that the input clock pin be located at one of the six ExpressCLK inputs of the device, and that a PIO FF be used.



5-4846(F).a

Figure 76. ExpressCLK to Output Delay

Timing Characteristics (continued)

Table 58. OR3C/Txxx Input to Fast Clock Setup/Hold Time (Pin-to-Pin)

OR3Cxx Commercial: $V_{DD} = 5.0 \text{ V} \pm 5\%$, $0^\circ\text{C} < T_A < 70^\circ\text{C}$; Industrial: $V_{DD} = 5.0 \text{ V} \pm 10\%$, $-40^\circ\text{C} < T_A < +85^\circ\text{C}$.OR3Txxx Commercial: $V_{DD} = 3.0 \text{ V to } 3.6 \text{ V}$, $0^\circ\text{C} < T_A < 70^\circ\text{C}$; Industrial: $V_{DD} = 3.0 \text{ V to } 3.6 \text{ V}$, $-40^\circ\text{C} < T_A < +85^\circ\text{C}$.

Description (T _J = 85 °C, V _{DD} = min)	Device	Speed								Unit
		-4		-5		-6		-7		
		Min	Max	Min	Max	Min	Max	Min	Max	
Output Not on Same Side of Device As Input Clock (Fast Clock Delays Using ExpressCLK Inputs)										
Input to FCLK Setup Time (middle ECLK pin)	OR3T20	—	—	0.00	—	0.00	—	0.00	—	ns
	OR3T30	—	—	0.00	—	0.00	—	0.00	—	ns
	OR3T55	0.00	—	0.00	—	0.00	—	0.00	—	ns
	OR3C/T80	0.00	—	0.00	—	0.00	—	0.00	—	ns
	OR3T125	—	—	0.00	—	0.00	—	0.00	—	ns
Input to FCLK Setup Time (middle ECLK pin, delayed data input)	OR3T20	—	—	0.80	—	0.58	—	2.20	—	ns
	OR3T30	—	—	0.74	—	0.55	—	2.17	—	ns
	OR3T55	0.29	—	0.62	—	0.51	—	2.11	—	ns
	OR3C/T80	0.14	—	0.50	—	0.46	—	2.06	—	ns
	OR3T125	—	—	0.22	—	0.33	—	1.90	—	ns
Input to FCLK Setup Time (corner ECLK pin)	OR3T20	—	—	0.00	—	0.00	—	0.00	—	ns
	OR3T30	—	—	0.00	—	0.00	—	0.00	—	ns
	OR3T55	0.00	—	0.00	—	0.00	—	0.00	—	ns
	OR3C/T80	0.00	—	0.00	—	0.00	—	0.00	—	ns
	OR3T125	—	—	0.00	—	0.00	—	0.00	—	ns
Input to FCLK Setup Time (corner ECLK pin, delayed data input)	OR3T20	—	—	0.00	—	0.00	—	0.00	—	ns
	OR3T30	—	—	0.00	—	0.00	—	0.00	—	ns
	OR3T55	0.00	—	0.00	—	0.00	—	0.00	—	ns
	OR3C/T80	0.00	—	0.00	—	0.00	—	0.00	—	ns
	OR3T125	—	—	0.00	—	0.00	—	0.00	—	ns
Input to FCLK Hold Time (middle ECLK pin)	OR3T20	—	—	4.29	—	3.72	—	3.27	—	ns
	OR3T30	—	—	4.50	—	3.80	—	3.35	—	ns
	OR3T55	6.33	—	4.97	—	3.96	—	3.52	—	ns
	OR3C/T80	6.95	—	5.49	—	4.15	—	3.72	—	ns
	OR3T125	—	—	6.36	—	4.47	—	4.05	—	ns

Notes:

The pin-to-pin timing parameters in this table should be used instead of results reported by ispLEVER.

The FCLK delays are for a fully routed clock tree that uses the ExpressCLK input into the fast clock network. It includes both the input buffer delay and the clock routing to the PFU CLK input. The delay will be reduced if any of the clock branches are not used.

Timing Characteristics (continued)

Table 63. Asynchronous Peripheral Configuration Mode Timing Characteristics

OR3Cxx Commercial: VDD = 5.0 V \pm 5%, 0 °C < TA < 70 °C; Industrial: VDD = 5.0 V \pm 10%, -40 °C < TA < +85 °C.

OR3Txx Commercial: VDD = 3.0 V to 3.6 V, 0 °C < TA < 70 °C; Industrial: VDD = 3.0 V to 3.6 V, -40 °C < TA < +85 °C.

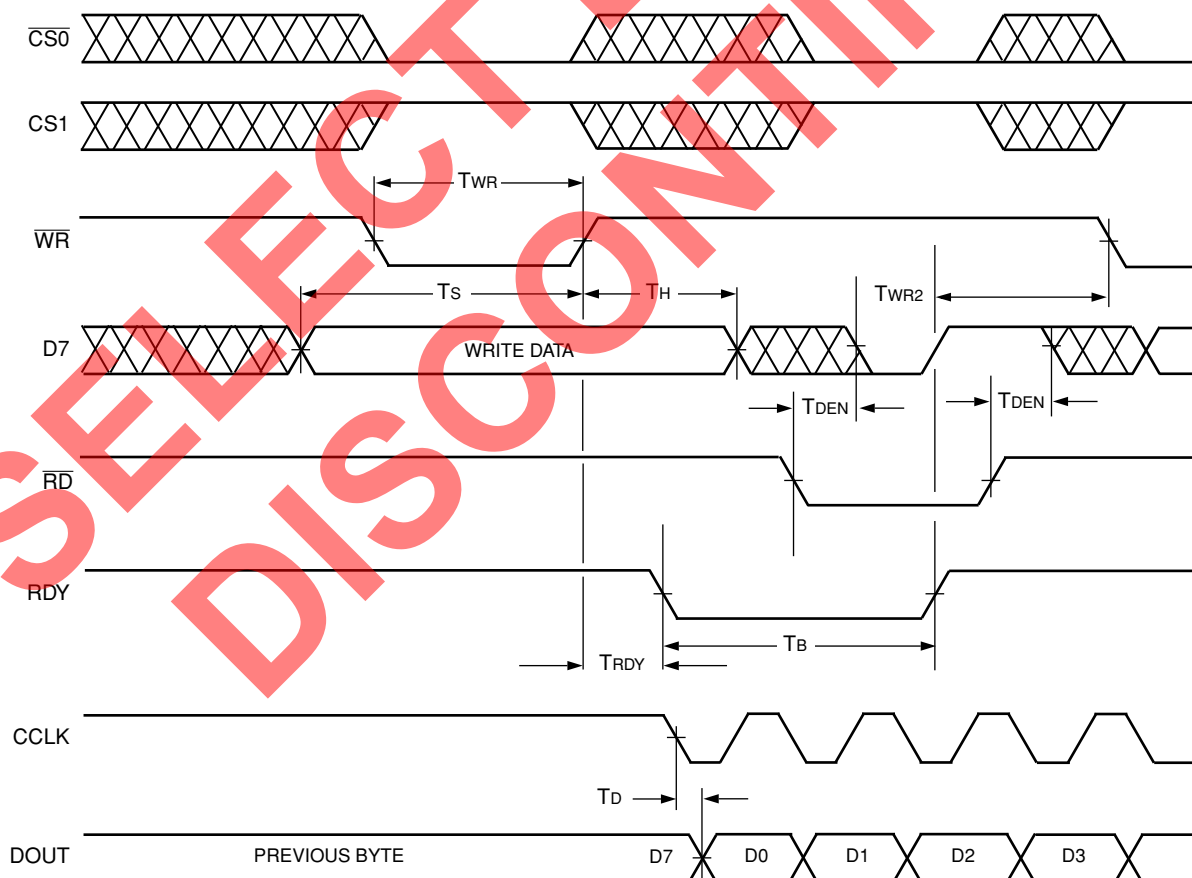
Parameter	Symbol	Min	Max	Unit
WR, CS0, and CS1 Pulse Width	TWR	50.00	—	ns
D[7:0] Setup Time: 3Cxx	TS	20.00	—	ns
3Txxx		10.50	—	ns
D[7:0] Hold Time	TH	0.00	—	ns
RDY Delay	TRDY	—	40.00	ns
RDY Low	TB	1.00	8.00	CCLK Periods
Earliest WR After RDY Goes High*	TWR2	0.00	—	ns
RD to D7 Enable/Disable	TDEN	—	40.00	ns
CCLK to DOUT	TD	—	5.00	ns

* This parameter is valid whether the end of not RDY is determined from the RDY pin or from the D7 pin.

Notes:

Serial data is transmitted out on DOUT on the falling edge of CCLK after the byte is input on D[7:0].

D[6:0] timing is the same as the write data portion of the D7 waveform because D[6:0] are not enabled by RD.



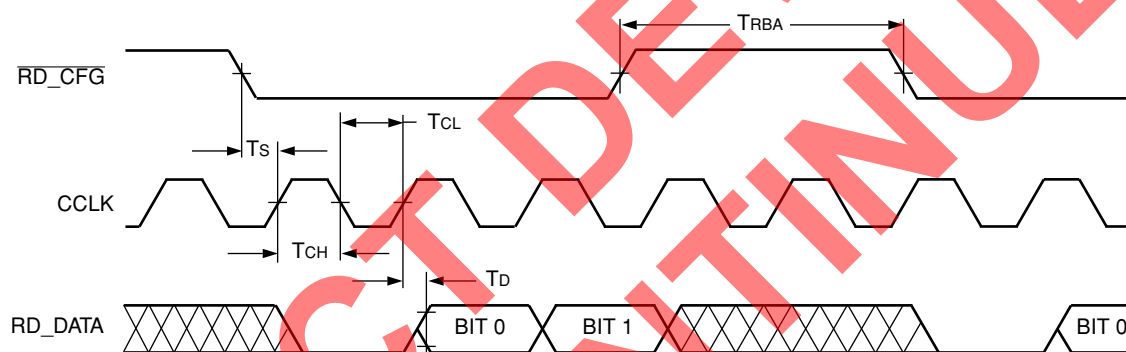
5-4533(F)

Figure 85. Asynchronous Peripheral Configuration Mode Timing Diagram

Timing Characteristics (continued)**Readback Timing****Table 66. Readback Timing Characteristics**OR3Cxx Commercial: VDD = 5.0 V \pm 5%, 0 °C < TA < 70 °C; Industrial: VDD = 5.0 V \pm 10%, -40 °C < TA < +85 °C.

OR3Txx Commercial: VDD = 3.0 V to 3.6 V, 0 °C < TA < 70 °C; Industrial: VDD = 3.0 V to 3.6 V, -40 °C < TA < +85 °C.

Parameter	Symbol	Min	Max	Unit
RD_CFG to CCLK Setup Time	TS	50.00	—	ns
RD_CFG High Width to Abort Readback	TRBA	2	—	CCLK cycles
CCLK Low Time	TCL	40.00	—	ns
CCLK High Time	TCH	40.00	—	ns
CCLK Frequency	Fc	—	12.50	MHz
CCLK to RD_DATA Delay	TD	—	40.00	ns



5-4536(F)

Figure 88. Readback Timing Diagram

Table 70. OR3T20 144-Pin TQFP Pinout

Pin	OR3T20 Pad	Function
1	VDD	VDD
2	VSS	VSS
3	PL1A	I/O-A0/MPI_BE0
4	PL2D	I/O
5	PL2A	I/O-A1/MPI_BE1
6	PL3D	I/O-A2
7	PL3A	I/O-A3
8	PL4D	I/O
9	PL4C	I/O
10	PL4A	I/O-A4
11	PL5D	I/O-A5
12	PL5C	I/O
13	PL5A	I/O-A6
14	VSS	VSS
15	PECKL	I-ECKL
16	PL6C	I/O
17	PL6A	I/O-A7/MPI_CLK
18	VDD	VDD
19	PL7D	I/O
20	PL7C	I/O
21	PL7A	I/O-A8/MPI_RW
22	VSS	VSS
23	PL8D	I/O-A9/MPI_ACK
24	PL8A	I/O-A10/MPI_BI
25	PL9D	I/O
26	PL9C	I/O
27	PL9A	I/O-A11/MPI_IRQ
28	PL10D	I/O-A12
29	PL10C	I/O
30	PL10A	I/O-A13
31	PL11A	I/O-A14
32	PL12D	I/O
33	PL12B	I/O-SECKLL
34	PL12A	I/O-A15
35	VSS	VSS
36	PCCLK	CCLK
37	VDD	VDD
38	VSS	VSS
39	PB1A	I/O-A16
40	PB1D	I/O
41	PB2A	I/O-A17
42	PB3A	I/O

Pin	OR3T20 Pad	OR3T30 Pad	OR3T55 Pad	Function
Y12	PB7D	PB8D	PB10D	I/O
W12	PB8A	PB9A	PB11A	I/O
V12	PB8B	PB9B	PB11B	I/O
U12	PB8C	PB9C	PB11C	I/O
Y13	PB8D	PB9D	PB11D	I/O
W13	PB9A	PB10A	PB12A	I/O-HDC
V13	PB9B	PB10B	PB12B	I/O
Y14	PB9C	PB10C	PB12C	I/O
W14	PB9D	PB10D	PB12D	I/O
Y15	PB10A	PB11A	PB13A	I/O-LDC
V14	PB10B	PB11B	PB13B	I/O
W15	PB10C	PB11C	PB13C	I/O
Y16	PB10D	PB11D	PB13D	I/O
U14	—	PB12A	PB14A	I/O
V15	—	PB12B	PB14D	I/O
W16	PB11A	PB12C	PB15A	I/O-INIT
Y17	—	—	PB15D	I/O
V16	—	PB12D	PB16A	I/O
W17	PB11B	PB13A	PB16D	I/O
Y18	PB11C	PB13B	PB17A	I/O
U16	PB11D	PB13C	PB17D	I/O
V17	PB12A	PB13D	PB17D	I/O
W18	PB12B	PB14A	PB18A	I/O
Y19	PB12C	PB14B	PB18B	I/O
V18	PB12D	PB14C	PB18C	I/O
W19	—	PB14D	PB18D	I/O
Y20	PDONE	PDONE	PDONE	DONE
W20	PRESETN	PRESETN	PRESETN	RESET
V19	PPRGMN	PPRGMN	PPRGMN	PRGM
U19	PR12A	PR14A	PR18A	I/O-M0
U18	—	PR14C	PR18C	I/O
T19	—	PR14D	PR18D	I/O
U20	—	PR13A	PR17A	I/O
U20	PR12B	PR18B	PR17B	I/O
T18	PR12C	PR13C	PR17C	I/O
T19	PR12D	PR13D	PR17D	I/O
T20	PR11A	PR16A	PR16A	I/O
R18	PR11B	PR12B	PR16D	I/O
P17	PR11C	PR12C	PR15A	I/O
R19	PR11D	PR12D	PR15C	I/O
R20	PR10A	PR11A	PR15D	I/O-M1
P18	PR10B	PR11B	PR14A	I/O
P19	PR10C	PR11C	PR14D	I/O
P20	PR10D	PR11D	PR13A	I/O
N18	PR9A	PR10A	PR12A	I/O-M2

Pin	OR3T20 Pad	OR3T30 Pad	OR3T55 Pad	Function
N19	PR9B	PR10B	PR12B	I/O
N20	PR9C	PR10C	PR12C	I/O
M17	PR9D	PR10D	PR12D	I/O
M18	PR8A	PR9A	PR11A	I/O-M3
M19	PR8B	PR9B	PR11B	I/O
M20	PR8C	PR9C	PR11C	I/O
L19	PR8D	PR9D	PR11D	I/O
L18	PR7A	PR8A	PR10A	I/O
L20	PR7B	PR8B	PR10B	I/O
K20	PR7C	PR8C	PR10C	I/O
K19	PR7D	PR8D	PR10D	I/O
K18	PECKR	PECKR	PECKR	I-ECKR
K17	PR6B	PR7B	PR9B	I/O
J20	PR6C	PR7C	PR9C	I/O
J19	PR6D	PR7D	PR9D	I/O
J18	PR5A	PR6A	PR8A	I/O
J17	PR5B	PR6B	PR8B	I/O
H20	PR5C	PR6C	PR8C	I/O
H19	PR5D	PR6D	PR8D	I/O
H18	PR4A	PR5A	PR7A	I/O-CS1
G20	PR4B	PR5B	PR7B	I/O
G19	PR4C	PR5C	PR7C	I/O
F20	PR4D	PR5D	PR7D	I/O
G18	PR3A	PR4A	PR6A	I/O-CS0
F19	PR3B	PR4B	PR6B	I/O
E20	PR3C	PR4C	PR5B	I/O
G17	PR3D	PR4D	PR5D	I/O
F18	PR2A	PR3A	PR4A	I/O-RD/MPI_STRB
E19	PR2B	PR3B	PR4B	I/O
D20	PR2C	PR3C	PR4D	I/O
E18	PR2D	PR3D	PR3A	I/O
D19	PR1A	PR2A	PR2A	I/O-WR
C20	PR1B	PR2B	PR2B	I/O
E17	PR1C	PR2C	PR2C	I/O
D18	PR1D	PR2D	PR2D	I/O
C19	—	PR1A	PR1A	I/O
B20	—	PR1B	PR1B	I/O
C18	—	PR1C	PR1C	I/O
B19	—	PR1D	PR1D	I/O
A20	PRD_CFGN	PRD_CFGN	PRD_CFGN	RD_CFG
A19	PT12D	PT14D	PT18D	I/O-SECKUR
B18	—	PT14C	PT18C	I/O
B17	PT12C	PT14B	PT18B	I/O
C17	PT12B	PT14A	PT18A	I/O
D16	PT12A	PT13D	PT17D	I/O-RDY/RCLK/MPI_ALE
A18	—	PT13C	PT17A	I/O

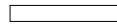
Pin	OR3T55 Pad	OR3C/T80 Pad	OR3T125 Pad	Function
R16	VSS	VSS	VSS	VSS*
T11	VSS	VSS	VSS	VSS*
T12	VSS	VSS	VSS	VSS*
T13	VSS	VSS	VSS	VSS*
T14	VSS	VSS	VSS	VSS*
T15	VSS	VSS	VSS	VSS*
T16	VSS	VSS	VSS	VSS*
AA23	VDD	VDD	VDD	VDD
AA4	VDD	VDD	VDD	VDD
AC11	VDD	VDD	VDD	VDD
AC16	VDD	VDD	VDD	VDD
AC21	VDD	VDD	VDD	VDD
AC6	VDD	VDD	VDD	VDD
D11	VDD	VDD	VDD	VDD
D16	VDD	VDD	VDD	VDD
D21	VDD	VDD	VDD	VDD
D6	VDD	VDD	VDD	VDD
F23	VDD	VDD	VDD	VDD
F4	VDD	VDD	VDD	VDD
L23	VDD	VDD	VDD	VDD
L4	VDD	VDD	VDD	VDD
T23	VDD	VDD	VDD	VDD
T4	VDD	VDD	VDD	VDD

*Thermally enhanced connection.

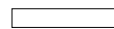
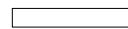
Package Outline Diagrams (continued)

208-Pin SQFP2

Dimensions are in millimeters.



11



5-3828(F)



DETAIL C (SQFP2 CHIP-UP)

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